Complementary Plastic Power Transistors

NPN/PNP Silicon DPAK For Surface Mount Applications

Designed for low voltage, low-power, high-gain audio amplifier applications.

Features

- Collector–Emitter Sustaining Voltage
 - $V_{CEO(sus)} = 25 \text{ Vdc (Min)} @ I_C = 10 \text{ mAdc}$
- High DC Current Gain $h_{FE} = 70$ (Min) @ $I_C = 500$ mAdc = 45 (Min) @ $I_C = 2$ Adc
 - = 10 (Min) @ $I_C = 5$ Adc
- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Low Collector-Emitter Saturation Voltage -
 - $V_{CE(sat)} = 0.3 \text{ Vdc (Max)} @ I_C = 500 \text{ mAdc}$ = 0.75 Vdc (Max) @ $I_C = 2.0 \text{ Adc}$
- High Current-Gain Bandwidth Product
 - $f_T = 65 \text{ MHz (Min)} @ I_C = 100 \text{ mAdc}$
- Annular Construction for Low Leakage
 - $I_{CBO} = 100 \text{ nAdc}$ @ Rated V_{CB}
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V
- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Base Voltage	V _{CB}	40	Vdc
Collector-Emitter Voltage	V_{CEO}	25	Vdc
Emitter-Base Voltage	V_{EB}	8.0	Vdc
Collector Current – Continuous – Peak	I _C	5.0 10	Adc
Base Current	ΙΒ	1.0	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	12.5 0.1	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.4 0.011	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

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SILICON POWER TRANSISTORS 5 AMPERES 25 VOLTS, 12.5 WATTS



DPAK CASE 369C STYLE 1

MARKING DIAGRAM



Y = Year

WW = Work Week

x = 1 or 0

G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	10	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	89.3	°C/W

^{2.} These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Sustaining Voltage (Note 3), (I _C = 10 mAdc, I _B = 0)		V _{CEO(sus)}	25	-	Vdc
Collector Cutoff Current		V _{CBO}	_ _	100 100	nAdc μAdc
Emitter Cutoff Current (V _{BE} = 8 Vdc, I _C = 0)		V _{EBO}	_	100	nAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3), $ \begin{aligned} &(I_C=500 \text{ mAdc, } V_{CE}=1 \text{ Vdc}) \\ &(I_C=2 \text{ Adc, } V_{CE}=1 \text{ Vdc}) \\ &(I_C=5 \text{ Adc, } V_{CE}=2 \text{ Vdc}) \end{aligned} $		h _{FE}	70 45 10	- 180 -	-
Collector–Emitter Saturation Voltage (Note 3) $ \begin{aligned} &(I_C=500 \text{ mAdc},\ I_B=50 \text{ mAdc})\\ &(I_C=2 \text{ Adc},\ I_B=200 \text{ mAdc})\\ &(I_C=5 \text{ Adc},\ I_B=1 \text{ Adc}) \end{aligned} $		V _{CE(sat)}	- - -	0.3 0.75 1.8	Vdc
Base-Emitter Saturation Voltage (Note 3), (I _C = 5 Adc, I _B = 1 Adc)		V _{BE(sat)}	_	2.5	Vdc
Base-Emitter On Voltage (Note 3), (I _C = 2 Adc, V _{CE} = 1 Vdc)		V _{BE(on)}	_	1.6	Vdc
DYNAMIC CHARACTERISTICS					
Current-Gain - Bandwidth Product (Note 4) (I _C = 100 mAdc, V _{CE} = 10 Vdc, f _{test} = 10 MHz)		f _T	65	-	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 0.1 MHz)	MJD200 MJD210	C _{ob}	- -	80 120	pF

^{3.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \approx 2%.

ORDERING INFORMATION

Device	Package Type	Shipping [†]	
MJD200	DPAK		
MJD200G	DPAK (Pb-Free)	75 Units / Rail	
MJD200RL	DPAK		
MJD200RLG	DPAK (Pb-Free)	1800 / Tape & Reel	
MJD200T4	DPAK		
MJD200T4G	DPAK (Pb-Free)	2500 / Tape & Reel	
MJD210	DPAK		
MJD210G	DPAK (Pb-Free)	75 Units / Rail	
MJD210RL	DPAK		
MJD210RLG	DPAK (Pb-Free)	1800 / Tape & Reel	
MJD210T4	DPAK	2500 / Tape & Reel	
MJD210T4G	DPAK (Pb-Free)		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{4.} $f_T = |h_{fe}| \cdot f_{test}$.

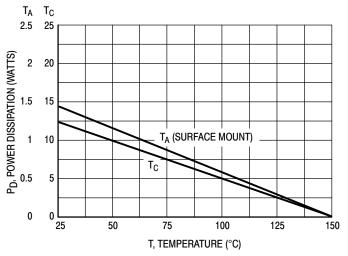
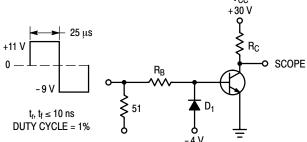


Figure 1. Power Derating



RB and RC VARIED TO OBTAIN DESIRED CURRENT LEVELS

D₁ MUST BE FAST RECOVERY TYPE, e.g.: 1N5825 USED ABOVE I_B \approx 100 mA MSD6100 USED BELOW I_B \approx 100 mA

FOR PNP TEST CIRCUIT, REVERSE ALL POLARITIES

Figure 2. Switching Time Test Circuit

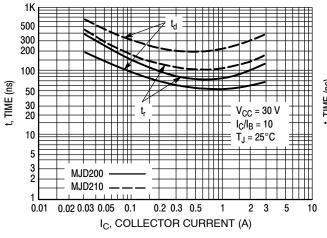


Figure 3. Turn-On Time

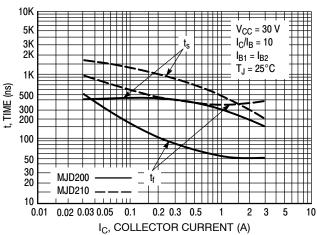


Figure 4. Turn-Off Time

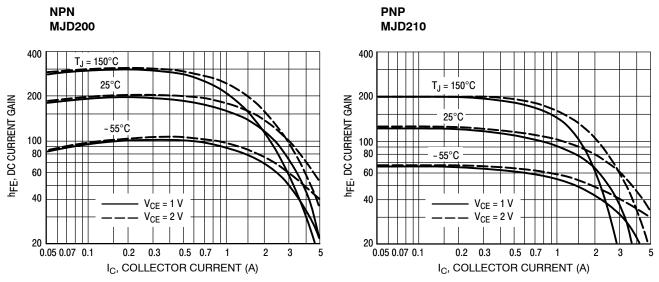


Figure 5. DC Current Gain

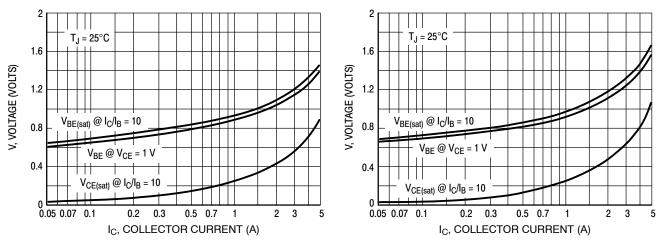


Figure 6. "On" Voltage

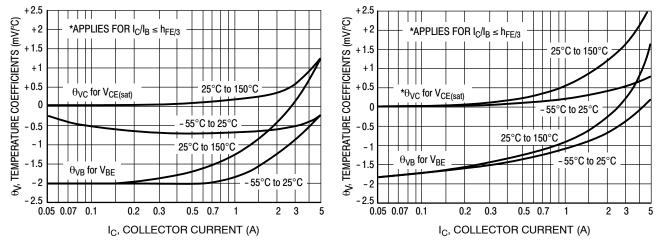


Figure 7. Temperature Coefficients

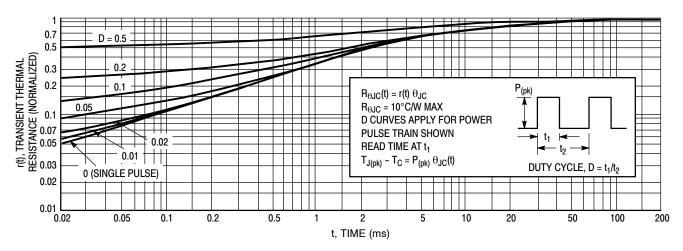


Figure 8. Thermal Response

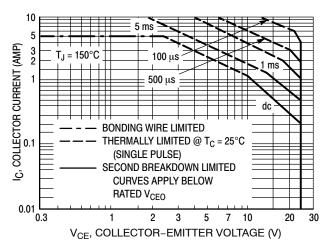


Figure 9. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 9 is based on $T_{J(pk)} = 150^{\circ}C$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ}C$. $T_{J(pk)}$ may be calculated from the data in Figure 8. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

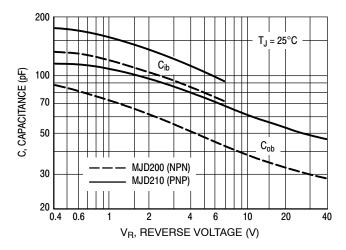
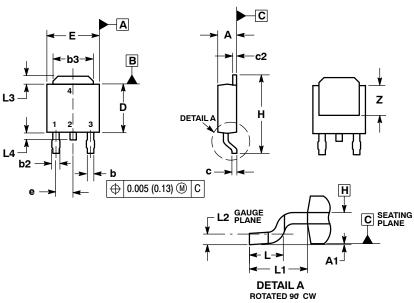


Figure 10. Capacitance

PACKAGE DIMENSIONS

DPAK CASE 369C-01 ISSUE D

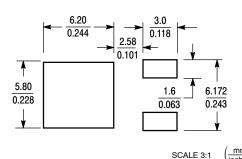


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 2. OSTRIBLING DIMENSION. INCLUS.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS, MOLD FLASH, PROTRUSIONS, OR BURRS, MOLD FLASH, PROTRUSIONS, OR BURRS. FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

SOLDERING FOOTPRINT*



STYLE 1: PIN 1. BASE

2. COLLECTOR 3. EMITTER

COLLECTOR

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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